



TECHNICAL DATA SHEET

CATEGORY: Industrial Alloys

Alloy

NAME: 5S "HMP" Solder

Solid Wire

SPECIFICATION –BS EN ISO 9453 Alloy 191 Replaces BS219 5S

FEATURES

- Melting Point - 296-301°C
- Working Temperature - 350-460°C
- Density - 11.1 gram/Cm³
- Tensile Strength - 30 MPA
- Brinell Hardness - Not Tested
- Uniform Elongation - 1.09

DESCRIPTION

AIM Solder HMP Solder is ideal for soldering applications that require maximum reliability of solder joints, especially for surface mounted components, through hole and final assembly, only solder of the highest purity is acceptable.

Other forms available on request subject to production capability

MAJOR ALLOY INGREDIENTS IN PERCENT

Sn	Ag	Pb	Others
4-5%	1-2%	92-94%	Trace

HANDLING

- There are no special handling or storage requirements for this product. This product should be limited to professional users only.

FLUX COMPATIBILITY

- HMP alloys are compatible with most electronic and industrial grade fluxes.

CLEANING

- Refer to data sheets provided by the flux manufacturer.

SAFETY

- Use with adequate ventilation and proper personal protective equipment.
- Refer to the accompanying **Safety Data Sheet** for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.